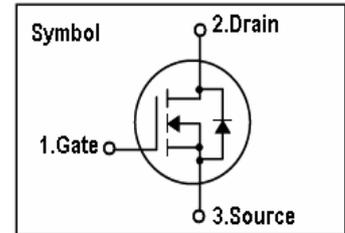




N-Channel MOSFET

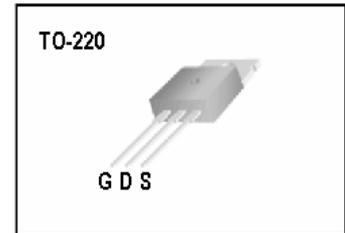
Features

- 70V,200A,Rds(on)(typ)=3.5mΩ @Vgs=10V
- High Ruggedness
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability



General Description

This Power MOSFET is produced using DeXin's advanced Trench MOS Technology. This latest technology has been especially designed to minimize on-state resistance, have a high rugged avalanche characteristics. These devices are well suited for low voltage application such as automotive,DC/DC converters,and high efficiency switch for power management in portable and battery products.



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V _{DSS}	Drain-Source Voltage	70	V
I _D	Continuous Drain Current (T _C =25 °C)	200	A
	Continuous Drain Current (T _C =100°C)	140	A
I _{DM}	Pulsed Drain Current (Note 1)	800	A
V _{GS}	Gate-Source Voltage	±25	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	1000	mJ
P _D	Maximum Power Dissipation (T _C =25 °C)	400	W
	Derating Factor above 25°C	2.0	W/°C
T _J	Operating Junction Temperature Range	-55 to +175	°C
T _{STG}	Storage Temperature Range	-55 to +175	°C

Thermal Characteristics

Symbol	Parameter	Max.	Units
R _{th j-c}	Thermal Resistance, Junction to case	0.5	°C / W
R _{th c-s}	Thermal Resistance, Case to Sink	0.5	°C / W
R _{th j-a}	Thermal Resistance, Junction to Ambient	62.5	°C / W



Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	70	-	-	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=70V, V_{GS}=0V$	-	-	250	μA
I_{GSS}	Gate Leakage Current, Forward	$V_{GS}=25V, V_{DS}=0V$	-	-	100	nA
	Gate Leakage Current, Reverse	$V_{GS}=-25V, V_{DS}=0V$	-	-	-100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	-	4	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=80A$	-	3.5	4.0	m Ω
Q_g	Total Gate Charge	$V_{DD}=60V$	-	212	-	nC
Q_{gs}	Gate-Source Charge	$V_{GS}=10V$	-	51	-	nC
Q_{gd}	Gate-Drain Charge	$I_D=80A$ (Note 3)	-	90	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=60V, V_{GS}=10V$	-	28	-	ns
t_r	Turn-on Rise Time	$I_D=90A, R_G=2.2\Omega$	-	40	-	ns
$t_{d(off)}$	Turn-off Delay Time	$T_C=25^\circ\text{C}$	-	38	-	ns
t_f	Turn-off Fall Time	(Note 3)	-	28	-	ns
C_{iss}	Input Capacitance -	$V_{DS}=25V$	-	7400	-	pF
C_{oss}	Output Capacitance	$V_{GS}=0V$	-	940	-	pF
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$	-	480	-	pF

Source-Drain Diode Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I_S	Continuous Source Diode Forward Current		-	-	200	A
I_{SM}	Pulsed Source Diode Forward Current (Note 1)		-	-	400	A
V_{SD}	Forward On Voltage	$V_{GS}=0V, I_S=90A$	-	-	1.5	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V, I_S=90A$	-	120	160	ns
Q_{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	420	630	nC

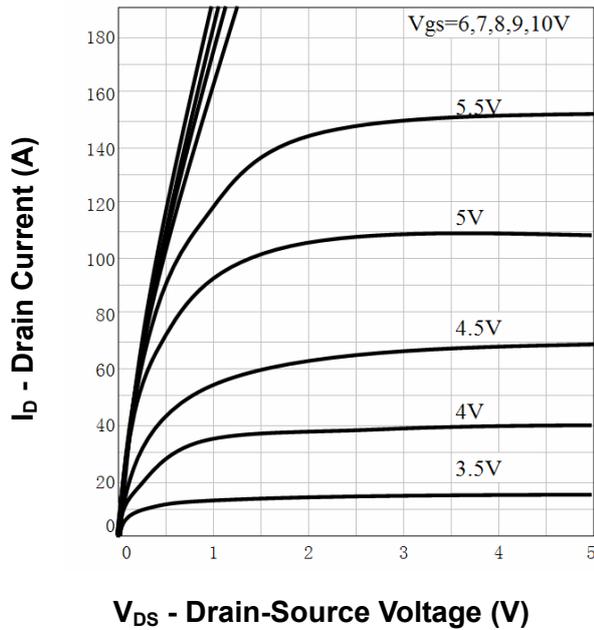
Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L=0.28\text{mH}, I_{AS}=50A, V_{DD}=45V, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$
3. Pulse Width $\leq 300\mu s$; Duty Cycle $\leq 2\%$

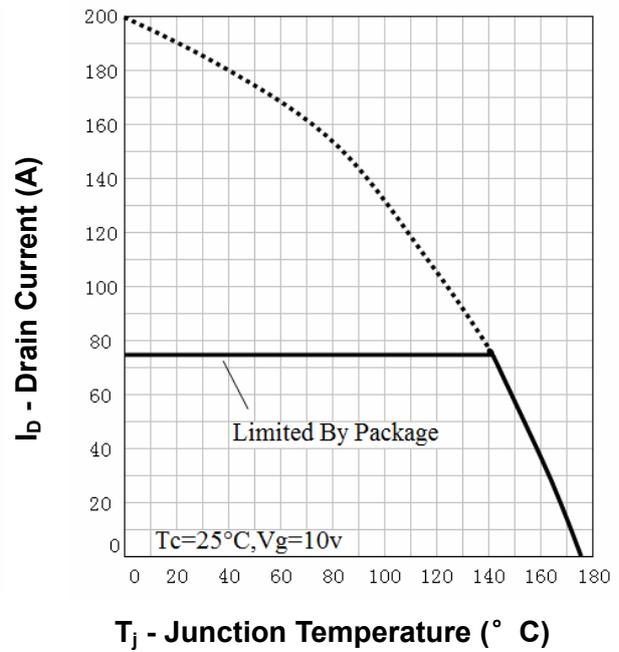


Typical Characteristics

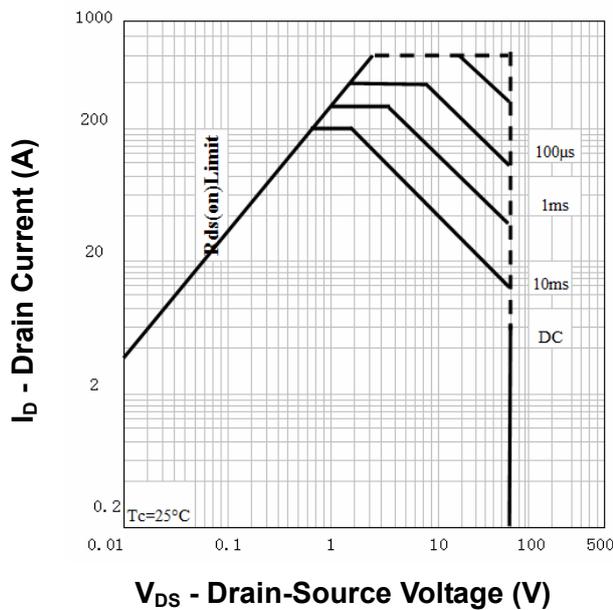
Output Characteristics



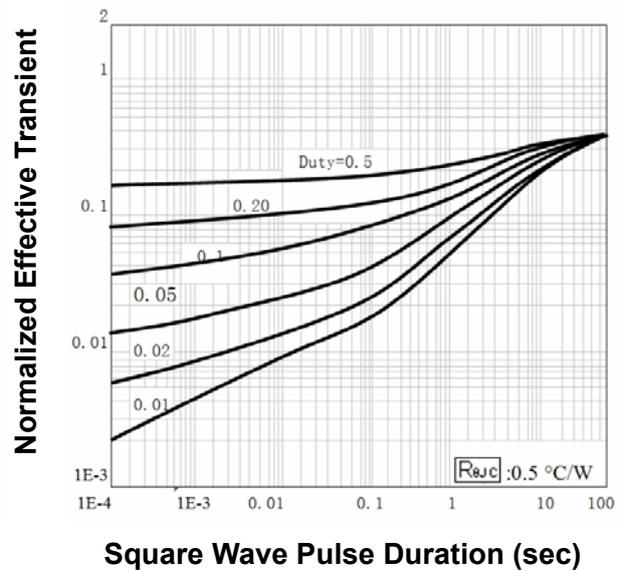
Drain Current



Safe Operation Area



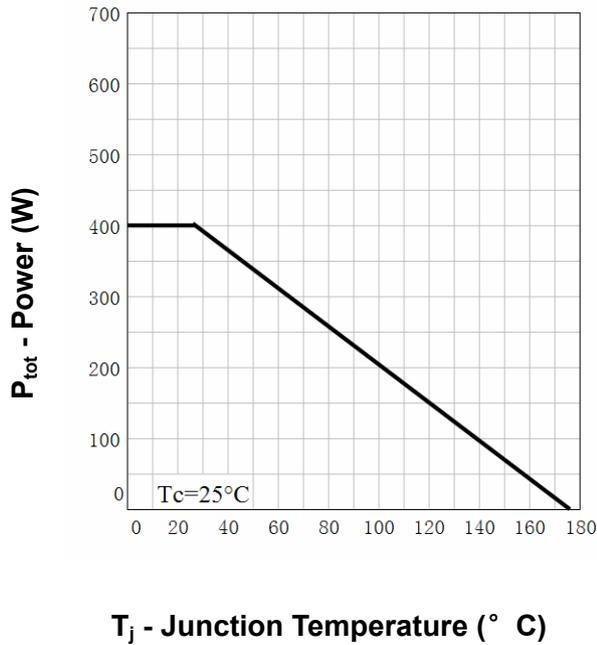
Thermal Transient Impedance



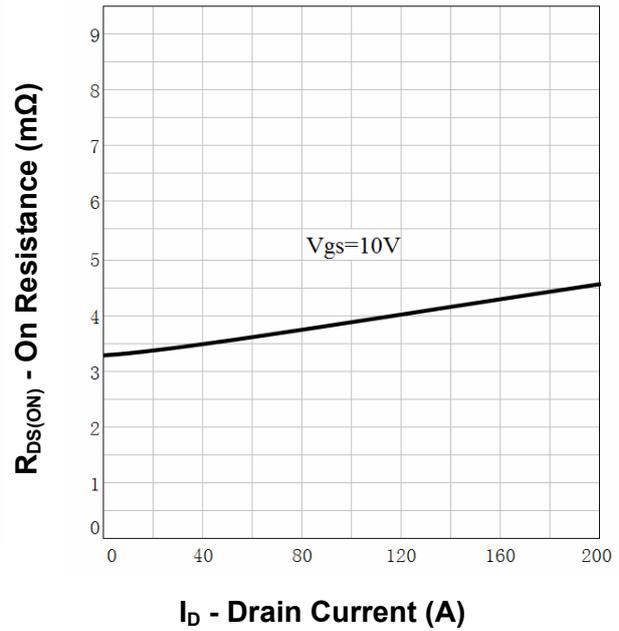


Typical Characteristics

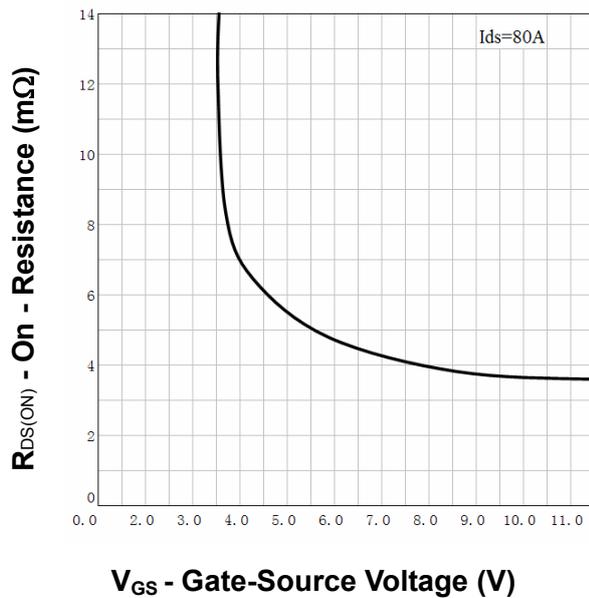
Power Dissipation



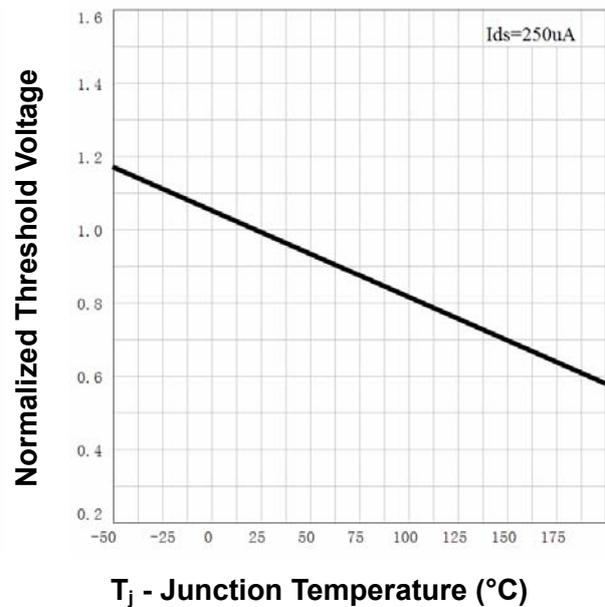
Drain-Source On Resistance



Drain-Source On Resistance

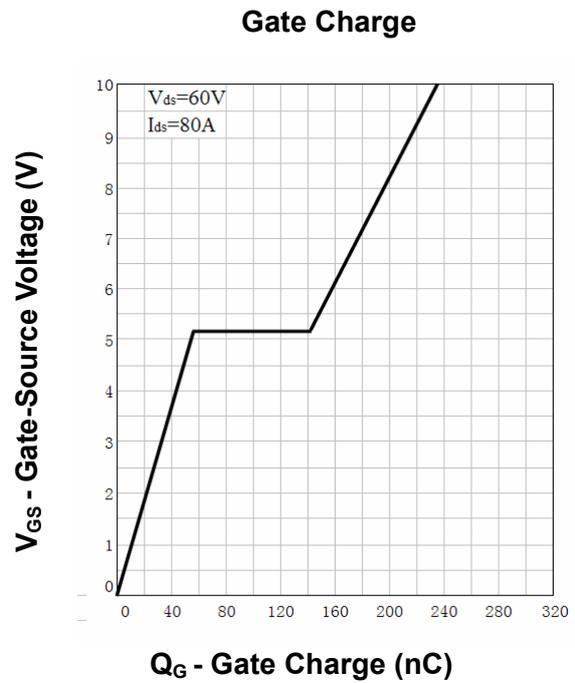
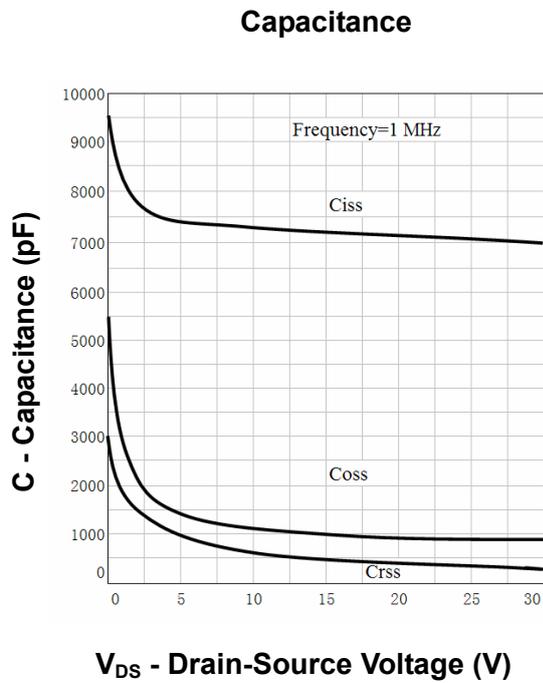
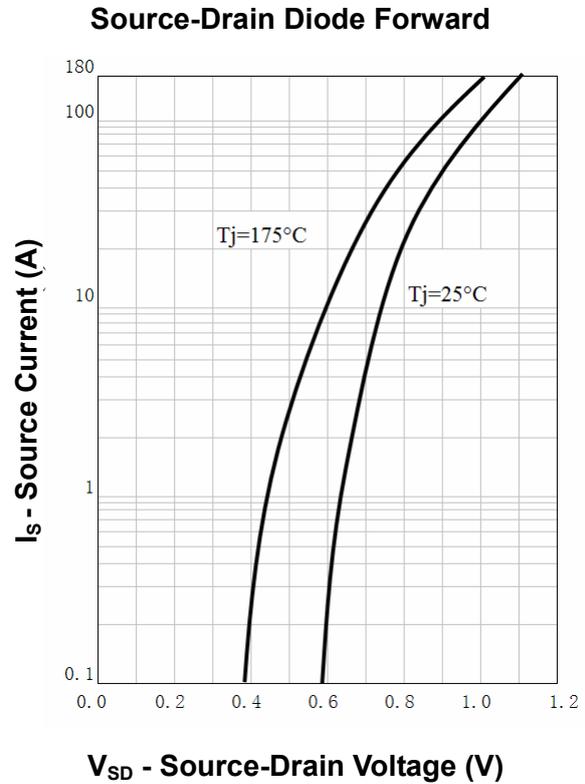
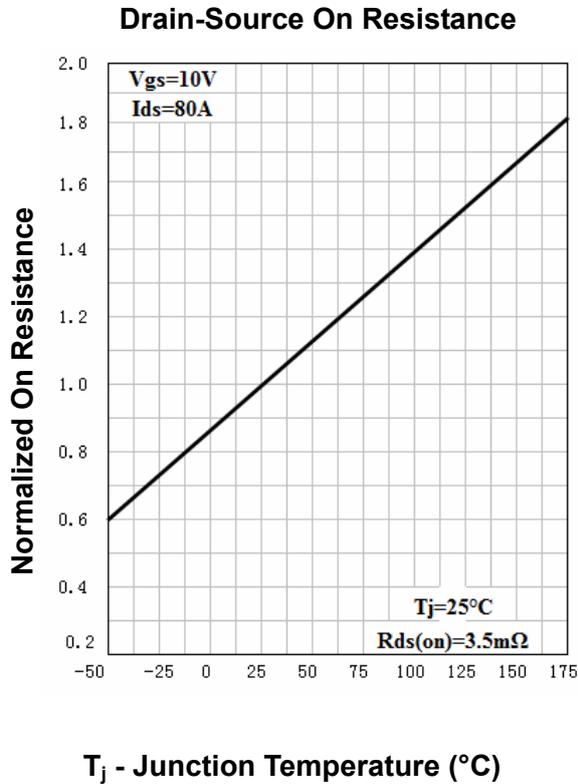


Gate Threshold Voltage



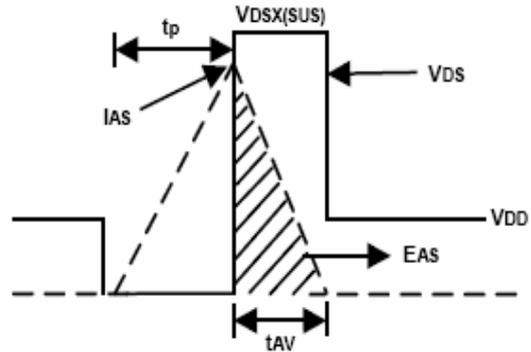
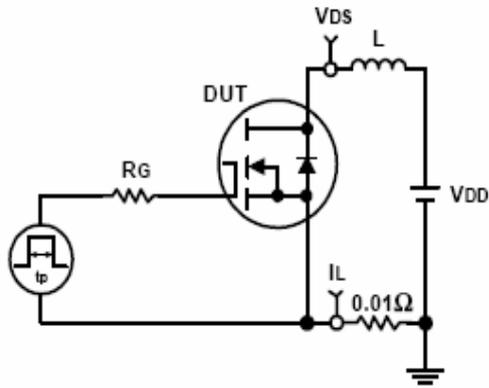


Typical Characteristics





Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms

